



Product Summary (@T_A = +25°C)

V _{RRM} (V)	I ₀ (A)	V _F (MAX) (V)	Ι _{R(MAX)} (μΑ)
600	2	1.7	5

Description and Applications

The US2JDFQ is a rectifier packaged in the low profile D-FLAT package. Providing ultra-fast recovery time for high efficiency, this device is ideal for use in applications such as:

- Reverse Protection
- Switching
- Blocking

2.0A SURFACE MOUNT ULTRA-FAST RECTIFIER

Features and Benefits

- Glass Passivated Die Construction
- Ultra-Fast Recovery Time for High Efficiency
- Surge Overload Rating to 50A Peak
- High Current Capability
- Low Profile Design, Package Height less than 1.1mm
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standard for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.036 grams (Approximate)

D-FLAT



Top View

Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
US2JDFQ-13	Automotive	D-FLAT	10,000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

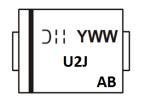
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



U2J= Product Type Marking Code)!! = Manufacturer's Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 4 for 2014) WW = Week Code (01 to 53) AB = Foundry and Assembly Code



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.				
Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 6)		V _{RRM} V _{RWM} V _R	600	V
RMS Reverse Voltage		V _{R(RMS)}	420	V
Average Rectified Output Current	@ T _T = +75°C	lo	2.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load		I _{FSM}	50	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal	R _{θJT}	22	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Minimum Reverse Breakdown Voltage (Note 6)	@I _R = 5μA	V _{(BR)R}	600	V
Maximum Forward Voltage Drop		VF	1 7	V
@ I _F = 1.0A		VF	1.7	v
Peak Reverse Current	@ T _A = +25°C		5.0	
at Rated DC Blocking Voltage (Note 6)	@ T _A = +100°C	IR	100	μA
Maximum Reverse Recovery Time (Note 7)		t _{RR}	75	ns
Typical Total Capacitance (Note 10)		CT	10	pF

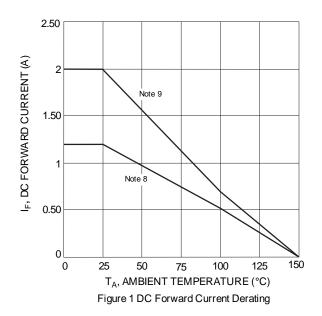
Notes: 6. Short duration pulse test used to minimize self-heating effect.

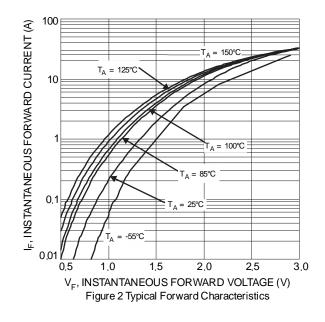
7. Measured with $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$. See Figure 7.

8. Device mounted on FR-4 substrate, 1inch × 1inch, 2oz, single-sided, PC boards with 0.1inch × 0.15inch copper pads.

9. Device mounted on FR-4 substrate, 0.4inch x 0.5inch, 2oz, single-sided, PC boards with 0.2inch x 0.25inch copper pads.

10. Measured at f=1.0MHz and applied reverse voltage of 4.0V $\breve{\text{DC}}.$







US2JDFQ

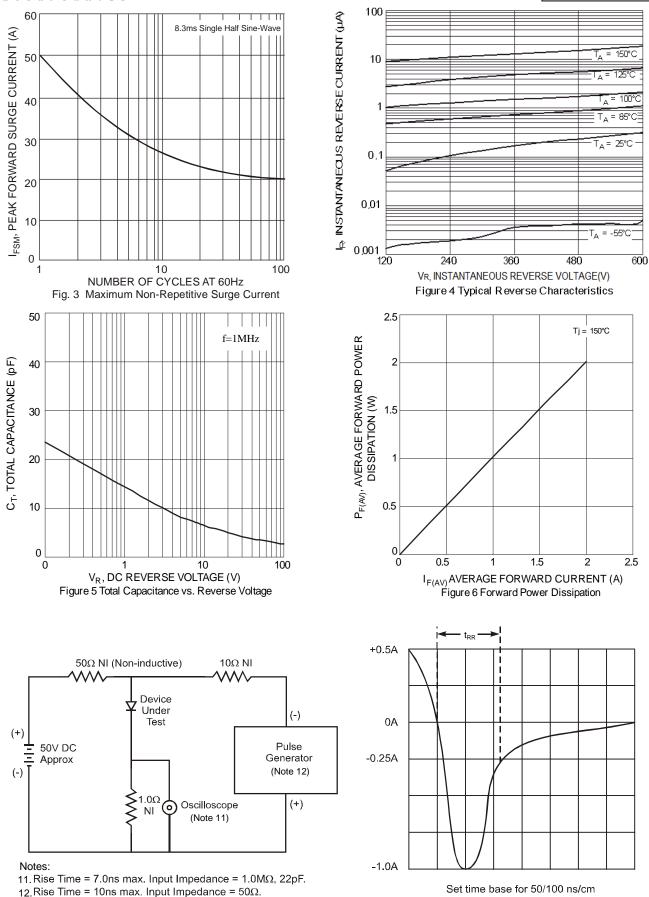


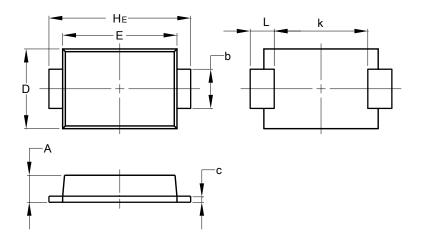
Fig. 7 Reverse Recovery Time Characteristic and Test Circuit

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Package Outline Dimensions

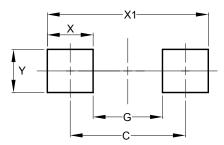
Please see http://www.diodes.com/package-outlines.html for the latest version.



D-FLAT				
Dim	Min	Max		
Α	0.90	1.10		
b	1.25	1.65		
С	0.10	0.40		
D	2.25	2.95		
Е	3.95	4.60		
k	2.80	-		
HE	5.00	5.60		
L	0.50	1.30		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.65
G	2.80
Х	1.85
X1	6.50
Y	1.70



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